

<b>PATENT ASSIGNMENT COVER SHEET</b>
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EPAS ID: PAT5539994

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
NOZOMU WASHIO	01/22/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	RIKEN TECHNOS CORPORATION
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16463994
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<b>Fax Number:</b>	
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<b>NAME OF SUBMITTER:</b>	ESMERALDA MENDOZA
<b>SIGNATURE:</b>	/Brad Y. Chin/
<b>DATE SIGNED:</b>	05/24/2019
<b>Total Attachments: 2</b>	
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source=Assignment_A00146US01CB#page2.tif	

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Docket No.

ASSIGNMENT

WHEREAS, I, Nozomu WASHIO, am the inventor of "HARDCOAT MULTILAYER FILM", for which application for United States Letters Patent was filed on May 24, 2019, as U.S. Application No. 16/463,994 (responsible attorney has authorization to fill in serial number and filing date upon filing); and

WHEREAS, RIKEN TECHNOS CORPORATION, whose post office address is 2-101, Kanda-Awajicho, Chiyoda-ku, Tokyo 1018336, Japan, a corporation created and existing under and by virtue of the laws of Japan, is desirous of acquiring the entire right, title and interest in and to the aforesaid invention throughout the world, and all right, title and interest in, to and under any and all Letters Patent of the United States and all other countries throughout the world; and

NOW, THEREFORE, be it known by all whom it may concern that for and in consideration of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, I the inventor hereby sell, assign, transfer, and set over to RIKEN TECHNOS CORPORATION, all right, title and interest in and to the said invention throughout the entire world, in and to said application for U.S. Letters Patent, and any and all divisions, continuations, substitutions, continuations-in-part, and reissues thereof, and any and all Letters Patent of the United States and foreign countries which may be granted therefore on such inventions or improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States. The assignments and transfers described herein are to be held and enjoyed by RIKEN TECHNOS CORPORATION for its own use and benefit, and for the use and benefit of its successors, assigns, or other legal representatives, to the end of the term or terms for which said Letters Patent of the United States or foreign countries are or may be granted or reissued, as fully and entirely as the same would have been held and enjoyed by me if this assignment and sale had not been made. I further hereby assign and transfer to said corporation whatever cause of action I may have for past or present infringement of said invention, together with the right to bring suit for any such infringement and to seek and receive damages and other relief arising from any such infringement.

I the inventor do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all Letters Patent of the United States on said invention or resulting from said application and from any and all divisions, continuations, and reissues thereof, to RIKEN TECHNOS CORPORATION, as assignee of my entire interest, and hereby covenant that I have the full right to convey the entire interest herein assigned, and that I have not executed and will not execute any agreement in conflict herewith.

I the inventor do further hereby covenant and agree that I will, at any time, upon request, execute and deliver any and all papers that may be necessary or desirable to perfect the title of said invention and to such Letters Patent as may be granted therefore to RIKEN TECHNOS

Docket No.

CORPORATION, its successors, assigns, or other legal representatives and that if RIKEN TECHNOS CORPORATION, its successors, assigns or other legal representatives shall desire to file any divisional or continuation applications or to secure a reissue of such Letters Patent, or to file a disclaimer relating thereto, will upon request, sign all papers, make all rightful oaths and do all lawful acts requisite for the filing of such divisional or continuation application, or such application for reissue and for the procuring thereof, and for the filing of such disclaimer, without further compensation but at the expense of said assignee, its successors, or other legal representatives.

I the inventor do further covenant and agree that I will, at any time upon request, communicate to RIKEN TECHNOS CORPORATION, its successors, assigns or other legal representatives, such facts relating to said invention and Letters Patent or the file history thereof as maybe known to us, and testify as to the same in any interference or other litigation when requested so to do, without further compensation but at the expense of said assignee, its successors, or other legal representatives.

EXECUTED THIS 22<sup>nd</sup> day of January, 2019.

Nozomu Washio  
Nozomu WASHIO

Yasuhiko Itagaki  
WITNESS

Kiyotaka Suzuki  
WITNESS